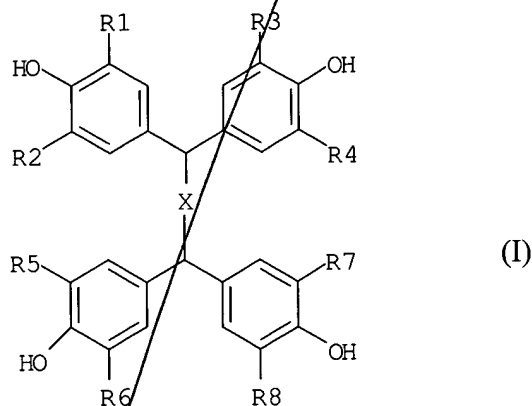


AMENDMENT D NEW CLAIMS 23-34

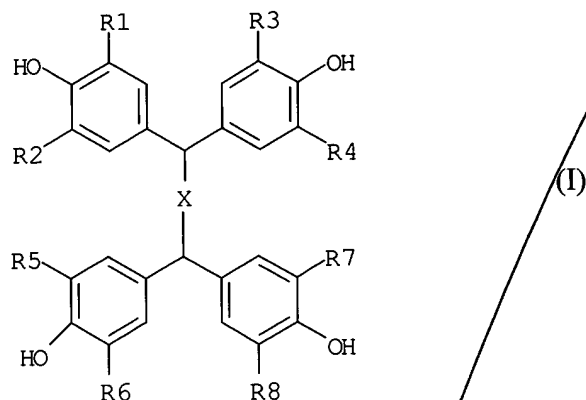
23. An epoxy resin composition comprising:
- a non-curing epoxy resin,
- a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin, and
- a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

24. The epoxy resin composition according to claim 23, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.
25. A method for curing an epoxy resin comprising a step of mixing a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst

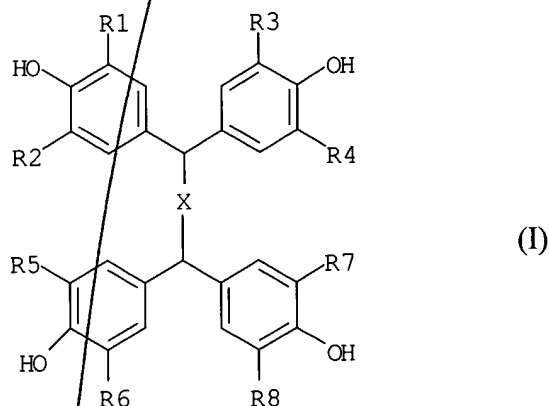
with a non-curing epoxy resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

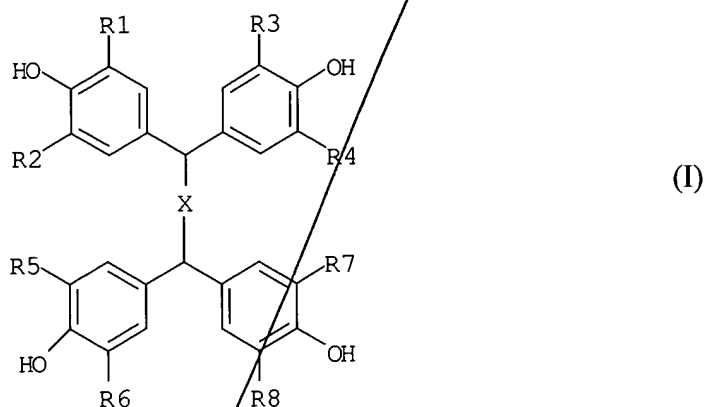
26. The method for curing an epoxy resin according to claim 25, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

27. A curative for epoxy resin, comprising a clathrate comprising:
a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group to cure an epoxy resin,



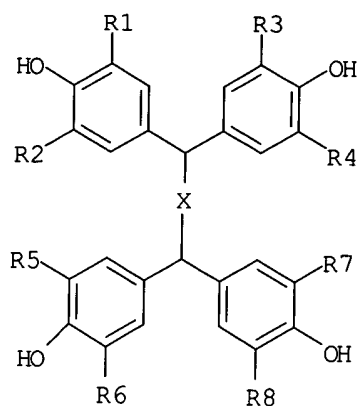
wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

28. A curing accelerator for epoxy resin, comprising a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

29. An epoxy resin composition, comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin,

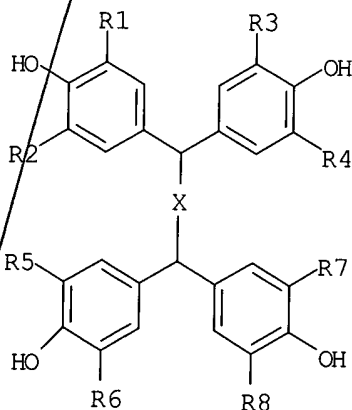


(I)

wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

30. An epoxy resin composition comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin; and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,

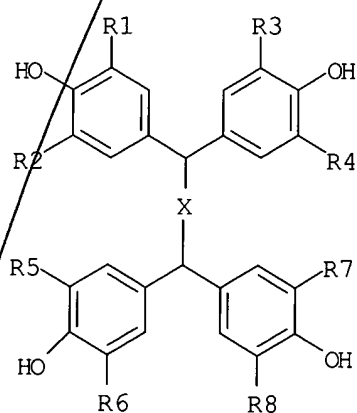


(I)

wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

31. The epoxy resin composition according to claim 29 or 30, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

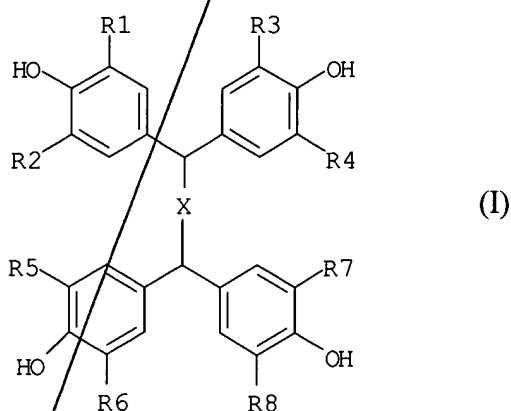
32. A method for curing an epoxy resin composition comprising the steps of:
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin is added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



(I)

wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

33. A method for curing an epoxy resin composition comprising the steps of:
 a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a
 compound reacting with an epoxy group of the epoxy resin to cure the resin, and
 a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a
 compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy
 resin are added and mixed to a non-curing epoxy resin, and then the mixture is heated to a
 predetermined temperature,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

34. The method for curing an epoxy resin composition according to claim 32 or 33, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.